



# HCE65R360

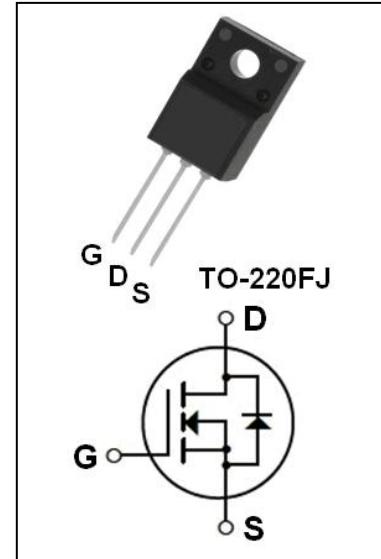
650V N-Channel Super Junction Power MOSFET

## ● Features:

- 11.0A, 650V,  $R_{DS(on)(Typ)}$  =330mΩ@ $V_{GS}=10V$
- Low Gate Charge
- Low  $C_{rss}$
- 100% Avalanche Tested
- Fast Switching
- Improved dv/dt Capability

## ● Application:

- High Frequency Switching Mode Power Supply
- Active Power Factor Correction



## Absolute Maximum Ratings( $T_c=25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Value	Unit
$V_{DSS}$	Drain-Source Voltage	650	V
$I_D$	Drain Current - Continuous( $T_c=25^{\circ}C$ )	11.0*	A
	- Continuous( $T_c=100^{\circ}C$ )	6.96*	A
$I_{DM}$	Drain Current -Pulsed (Note1)	44.0*	A
$V_{GSS}$	Gate-Source Voltage	$\pm 30$	V
$E_{AS}$	Single Pulsed Avalanche Energy ( Limit Reference Value ) (Note2)	233	mJ
$I_{AR}$	Avalanche Current (Note1)	5.5	A
$E_{AR}$	Repetitive Avalanche Energy (Note1)	5.5	mJ
$dv/dt$	Peak Diode Recovery $dv/dt$ (Note3)	8.5	V/ns
$P_D$	Power Dissipation( $T_c =25^{\circ}C$ ) -Derate above $25^{\circ}C$	35	W
		0.28	W/ $^{\circ}C$
$T_j$	Operating Junction Temperature	150	$^{\circ}C$
$T_{stg}$	Storage Temperature Range	-55 to+150	$^{\circ}C$

\* Drain Current Limited by Maximum Junction Temperature.

## Thermal Characteristics

Symbol	Parameter	Max	Unit
$R_{\theta JC}$	Thermal Resistance,Junction to Case	3.57	$^{\circ}C /W$
$R_{\theta JA}$	Thermal Resistance,Junction to Ambient	80	$^{\circ}C /W$



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## Electrical Characteristics(Tc=25°C unless otherwise noted)

Symbol	Parameter	Test Conditons	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
BV <sub>DSS</sub>	Drain-source Breakdown Voltage	V <sub>GS</sub> =0V ,I <sub>D</sub> =250μA	650	--	--	V
△BV <sub>DSS</sub> /△T <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> =250μA (Referenced to 25°C)	--	0.68	--	V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =650V,V <sub>GS</sub> =0V	--	--	1	μA
		V <sub>DS</sub> =520V,Tc=125°C	--	--	10	μA
I <sub>GSSF</sub>	Gate-Body Leakage Current,Forward	V <sub>GS</sub> =+30V, V <sub>DS</sub> =0V	--	--	100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current,Reverse	V <sub>GS</sub> =-30V, V <sub>DS</sub> =0V	--	--	-100	nA
<b>On Characteristics</b>						
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> =250μA	2.0	--	4.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =10 V, I <sub>D</sub> =5.5A	--	330	380	mΩ
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> =20 V, I <sub>D</sub> =5.5A (Note4)	--	7.0	--	S
<b>Dynamic Characteristics</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =25V,V <sub>GS</sub> =0V, f=1.0MHz	--	615	--	pF
C <sub>oss</sub>	Output Capacitance		--	270	--	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		--	40	--	pF
<b>Switching Characteristics</b>						
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = 325 V, I <sub>D</sub> = 11.0 A, R <sub>G</sub> = 25 Ω (Note4,5)	--	12.3	--	ns
t <sub>r</sub>	Turn-On Rise Time		--	35.2	--	ns
t <sub>d(off)</sub>	Turn-Off Delay Time		--	64	--	ns
t <sub>f</sub>	Turn-Off Fall Time		--	31.3	--	ns
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> = 520 V, I <sub>D</sub> = 11.0 A, V <sub>GS</sub> = 10 V (Note4,5)	--	23.1	--	nC
Q <sub>gs</sub>	Gate-Source Charge		--	5.5	--	nC
Q <sub>gd</sub>	Gate-Drain Charge		--	10.9	--	nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
I <sub>s</sub>	Maximum Continuous Drain-Source Diode Forward Current		--	--	11.0	A
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode Forward Current		--	--	44	A
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	V <sub>GS</sub> =0V,I <sub>s</sub> =11.0A	--	--	1.4	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> =0V, I <sub>s</sub> =11.0A, d I <sub>F</sub> /dt=100A/μs (Note4)	--	363	--	ns
Q <sub>rr</sub>	Reverse Recovery Charge		--	3.95	--	μC

### Notes:

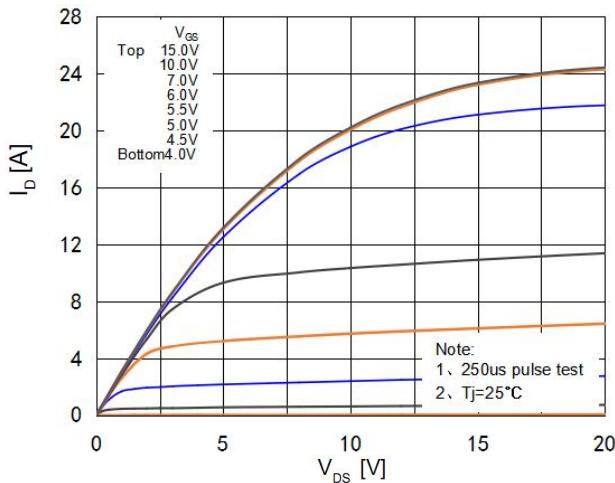
- 1、Repetitive Rating:Pulse Width Limited by Maximum Junction Temperature.
- 2、L = 14mH, I<sub>AS</sub> =5.5A, V<sub>DD</sub> = 100V, R<sub>G</sub> = 25 Ω, Starting T<sub>J</sub> = 25°C.
- 3、I<sub>SD</sub>≤11.0A, di/dt≤200A/μs, V<sub>DD</sub>≤BV<sub>DSS</sub>, Starting T<sub>J</sub> = 25°C.
- 4、Pulse Test : Pulse Width ≤300 μ s, Duty Cycle≤2%.
- 5、Essentially Independent of Operating Temperature.



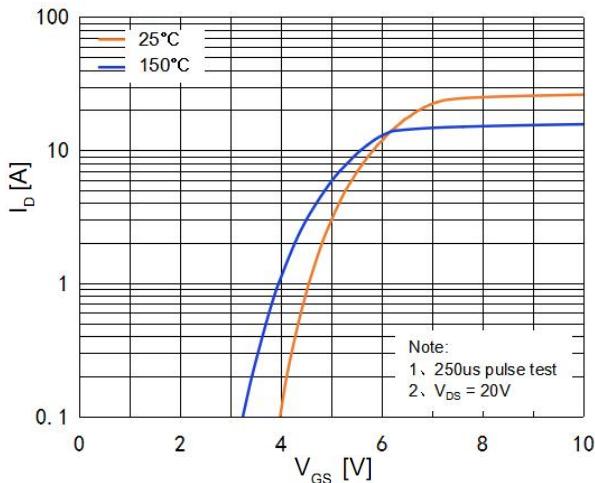
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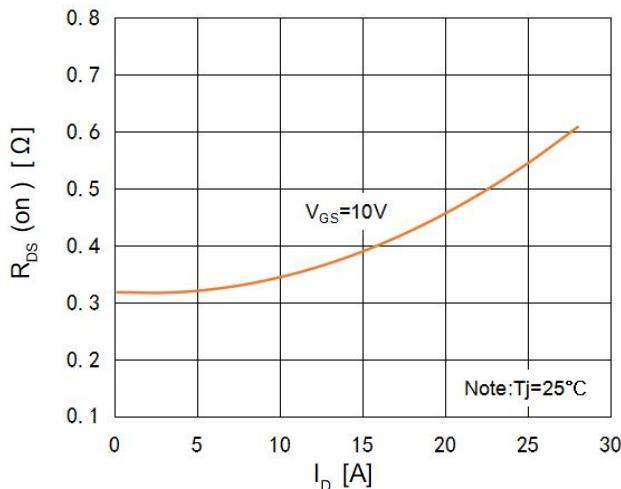
### On-Region Characteristics



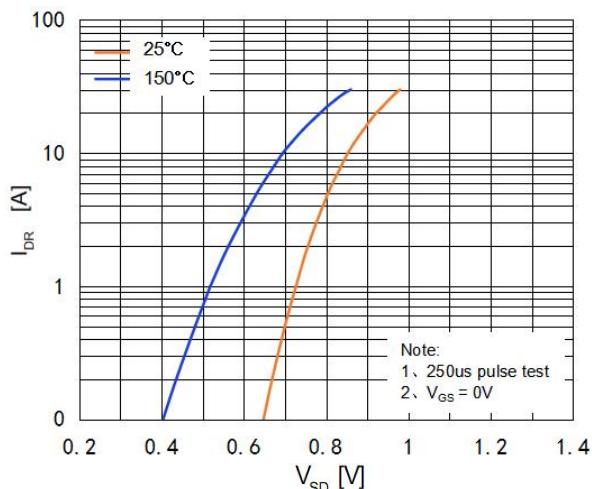
### Transfer Characteristics



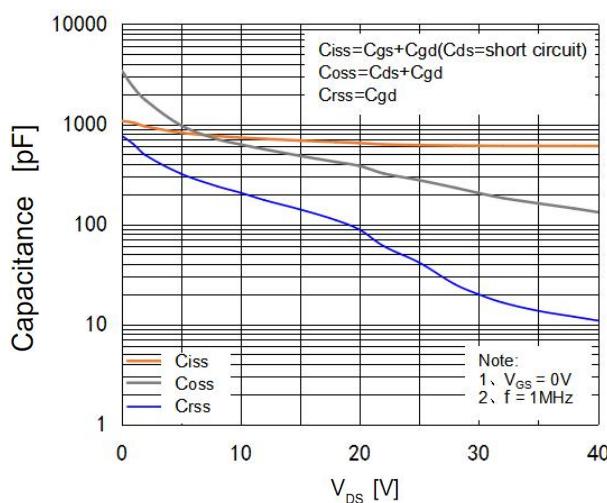
### On-Resistance Variation vs. Drain Current and Gate Voltage



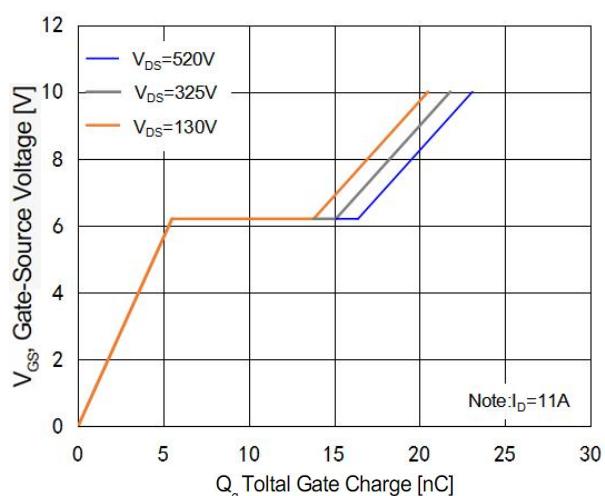
### Body Diode Forward Voltage Variation vs. Source Current and Temperature



### Capacitance Characteristics



### Gate Charge Characteristics

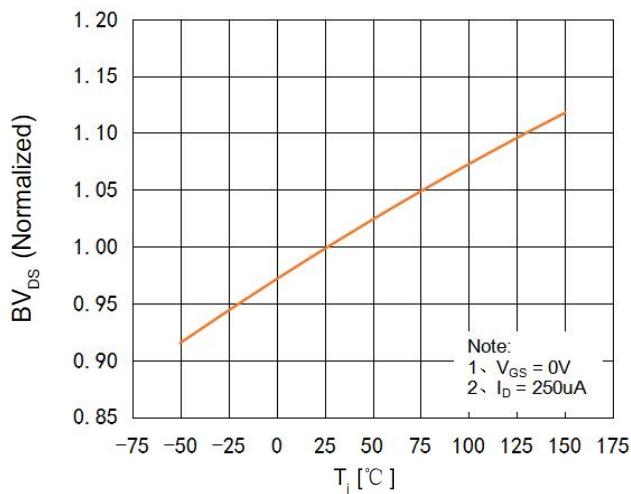




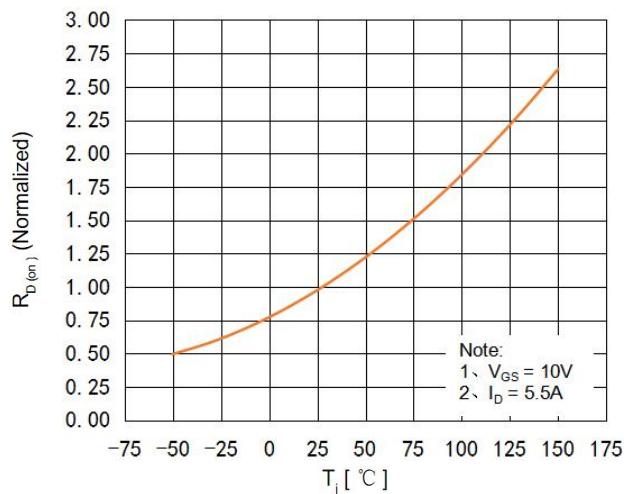
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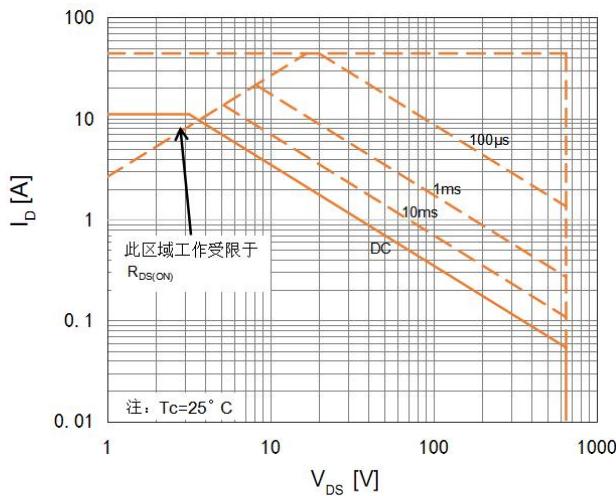
### Breakdown Voltage Variation vs. Temperature



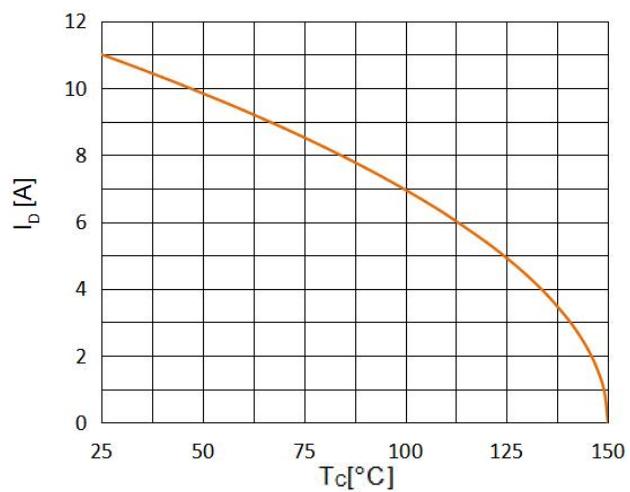
### On-Resistance Variation vs. Temperature



### Maximum Safe Operating Area



### Maximum Drain Current Vs. Case Temperature



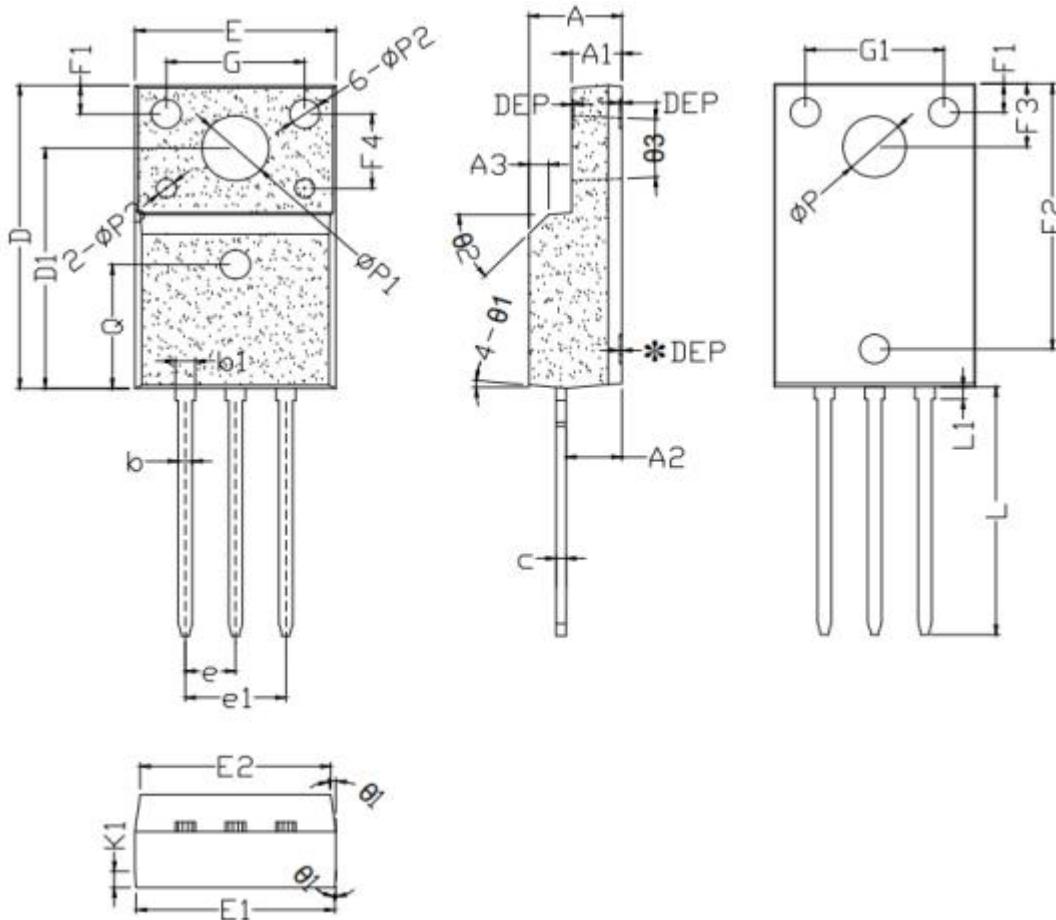
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**TO-220FJ (窄脚) Package Dimensions**

UNIT: mm

SYMBOL	min	nom	max	SYMBOL	min	nom	max
A	4.50	4.70	4.90	F3	3.10	3.30	3.50
A1	2.34	2.54	2.74	F4	3.70	3.90	4.10
A2	2.56	2.76	2.93	G1	6.80	7.00	7.20
A3		1.0REF		K1	0.60	0.70	0.80
b	0.60	0.70	0.80	L	11.98	12.98	13.98
b1	0.90	1.00	1.10	L1	-	-	0.95
c	0.40	0.50	0.60	Q		6.50REF	
D	15.47	15.87	16.27	ΦP	2.98	3.18	3.38
D1	12.17	12.57	12.97	ΦP1	3.20	3.40	3.60
e		2.54REF		ΦP2	1.30	1.50	1.70
e1		5.08REF		ΦP3	0.80	1.00	1.20
E	9.86	10.16	10.46	θ1	3°	5°	7°
E1	9.76	10.06	10.36	θ2	40°	45°	50°
E2	9.10	9.40	9.70	θ3	3°	5°	7°
F1	1.30	1.50	1.70	DEF	0.05	0.10	0.20
F2	13.60	13.90	14.20				





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注意事项：

- 1、在电路设计时请不要超过器件的最大额定值，否则会影响整机的可靠性。
- 2、MOSFET产品为静电敏感型器件，使用时应注意采取防静电保护措施，如佩戴防静电手环、设备接地等。
- 3、如需安装散热片，请注意控制扭力大小及散热片的平整度。
- 4、该规格书由华科公司制作，并可能不定期更改，恕不另行通知。
- 5、如有疑问，请及时联系我司销售代表。

版本履历表：

序号	版本号	修改时间	修改记录
1	V1.0	2022-12-20	首次发行